

Electronic components - Long-term storage of electronic semiconductor devices - Part 6: Packaged or Finished Devices

EESTI STANDARDI EESSÕNA

NATIONAL FOREWORD

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English Version

**Electronic components - Long-term storage of electronic
semiconductor devices - Part 6: Packaged or finished devices
(IEC 62435-6:2018)**

Composants électroniques - Stockage de longue durée des
dispositifs électroniques à semiconducteurs - Partie 6:
Dispositifs encapsulés ou finis
(IEC 62435-6:2018)

Elektronische Bauteile - Langzeitlagerung elektronischer
Halbleiterbauelemente - Teil 6: Bauelemente in Gehäusen
oder fertiggestellte Bauelemente
(IEC 62435-6:2018)

This European Standard was approved by CENELEC on 2018-10-03. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the CEN-CENELEC Management Centre or to any CENELEC member.

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

European foreword

The text of document 47/2482/FDIS, future edition 1 of IEC 62435-6, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 62435-6:2018.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2019-07-03
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2021-10-03

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Endorsement notice

The text of the International Standard IEC 62435-6:2018 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following notes have to be added for the standards indicated:

IEC 60721-3-1	NOTE	Harmonized as EN IEC 60721-3-1
IEC 62435-1	NOTE	Harmonized as EN 62435-1
IEC 62435-2	NOTE	Harmonized as EN 62435-2
IEC 62435-3 ¹	NOTE	Harmonized as EN IEC 62435-3 ²
IEC 62435-4	NOTE	Harmonized as EN IEC 62435-4
IEC 62435-5	NOTE	Harmonized as EN 62435-5
IEC 62435-7 ³	NOTE	Harmonized as EN IEC 62435-7 ⁴
IEC 62435-8 ⁵	NOTE	Harmonized as EN IEC 62435-8 ⁶

¹ Under preparation. Stage at the time of publication: IEC/CCDV 62435-3:2018.

² Under preparation. Stage at the time of publication: prEN IEC 62435-3:2018.

³ Under preparation. Stage at the time of publication: IEC/CD 62435-7:2018.

⁴ Under preparation. Stage at the time of publication: prEN IEC 62435-7:2018.

⁵ Under preparation. Stage at the time of publication: IEC/CD 62435-8:2018.

⁶ Under preparation. Stage at the time of publication: prEN IEC 62435-8:2018.

Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60749-20	-	Semiconductor devices - Mechanical and climatic test methods - Part 20: Resistance of plastic encapsulated SMDs to the combined effect of moisture and soldering heat	EN 60749-20	-
IEC 60749-20-1	-	Semiconductor devices - Mechanical and climatic test methods - Part 20-1: Handling, packing, labelling and shipping of surface-mount devices sensitive to the combined effect of moisture and soldering heat	EN 60749-20-1	-
JEDEC J-STD-020	-	Moisture/reflow classification for nonhermetic solid state surface mount devices		-
JEDEC J-STD-075	-	Classification of non-IC electronic components for assembly processes		-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**ELECTRONIC COMPONENTS – LONG-TERM STORAGE OF
ELECTRONIC SEMICONDUCTOR DEVICES –****Part 6: Packaged or finished devices****FOREWORD**

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International Standard IEC 62435-6 has been prepared by IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47/2482/FDIS	47/2495/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 62435 series, published under the general title *Electronic components – Long-term storage of electronic semiconductor devices*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

INTRODUCTION

This document applies to the long-term storage of electronic components.

This is a standard for long-term storage (LTS) of electronic devices drawing on the best long-term storage practices currently known. For the purposes of this standard, LTS is defined as any device storage whose duration can be more than 12 months for product scheduled for long duration storage. While intended to address the storage of unpackaged semiconductors and packaged electronic devices, nothing in this document precludes the storage of other items under the storage levels defined herein.

Although it has always existed to some extent, obsolescence of electronic components and particularly of integrated circuits, has become increasingly intense over the last few years.

Indeed, with the existing technological boom, the commercial life of a component has become very short compared with the life of industrial equipment such as that encountered in the aeronautical field, the railway industry or the energy sector.

The many solutions enabling obsolescence to be resolved are now identified. However, selecting one of these solutions should be preceded by a case-by-case technical and economic feasibility study, depending on whether storage is envisaged for field service or production, for example:

- remedial storage as soon as components are no longer marketed;
- preventive storage anticipating declaration of obsolescence.

Taking into account the expected life of some installations, sometimes covering several decades, the qualification times, and the unavailability costs, which can also be very high, the solution to be adopted to resolve obsolescence should often be rapidly implemented. This is why the solution retained in most cases consists in systematically storing components which are in the process of becoming obsolescent.

The technical risks of this solution are, a priori, fairly low. However, it requires perfect mastery of the implemented process and especially of the storage environment, although this mastery becomes critical when it comes to long-term storage.

All handling, protection, storage and test operations are recommended to be performed according to the state of the art.

The application of the approach proposed in this document in no way guarantees that the stored components are in perfect operating condition at the end of this storage. It only comprises a means of minimizing potential and probable degradation factors.

Some electronic device users have the need to store electronic devices for long periods of time. Lifetime buys are commonly made to support production runs of assemblies that well exceed the production timeframe of its individual parts. This puts the user in a situation requiring careful and adequate storage of such parts to maintain the as-received solderability and minimize any degradation effects to the part over time. Major degradation concerns are moisture, electrostatic fields, ultraviolet light, large variations in temperature, air-borne contaminants, and outgassing.

Warranties and sparing also present a challenge for the user or repair agency as some systems have been designated to be used for long periods of time, in some cases for up to 40 years or more. Some of the devices needed for repair of these systems will not be available from the original component manufacturer for the lifetime of the system or the spare assembly can be built with the original production run but then requires long-term storage. This document was developed to provide a standard for storing electronic devices for long periods

of time. For storage of devices that are moisture sensitive but that do not need to be stored for long periods of time, IEC TR 62258-3 can be consulted.

Long-term storage assumes that the device is going to be placed in uninterrupted storage for a number of years. It is essential that it is useable after storage. Particular attention should be paid to storage media surrounding the devices together with the local environment.

These guidelines do not imply any warranty of product or guarantee of operation beyond the storage time given by the original component manufacturer.

The IEC 62435 series is intended to ensure that adequate reliability is achieved for devices in user applications after long-term storage. Users are encouraged to request data from suppliers to applicable specifications to demonstrate a successful storage life as requested by the user. These standards are not intended to address built-in failure mechanisms that would take place regardless of storage conditions.

These standards are intended to give practical guide to methods of long-duration storage of electronic components where this is intentional or planned storage of product for a number of years. Storage regimes for work-in-progress production are managed according to company internal process requirements and are not detailed in this series of standards.

The overall standard is split into a number of parts. Parts 1 to 4 apply to any long-term storage and contain general requirements and guidance, whereas Parts 5 to 9 specific to the type of product being stored. It is intended that the product specific part should be read alongside the general requirements of Parts 1 to 4.

Electronic components requiring different storage conditions are planned to be covered separately starting with Part 5.

The structure of the IEC 62435 series as currently conceived is as follows:

- Part 1 – General
- Part 2 – Deterioration mechanisms
- Part 3 – Data
- Part 4 – Storage
- Part 5 – Die and wafer devices
- Part 6 – Packaged or finished devices
- Part 7 – MEMS
- Part 8 – Passive electronic devices
- Part 9 – Special cases